TOSHIBA TLRMH265P

TOSHIBA LED LAMP InGaA&P RED LIGHT EMISSION

- 5 mm DIAMETER
- InGaAlP RED LED
- Diffused Milky White Lens
- Low Drive Current, High Intensity Red Light Emission
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- Straight Lead Type
- Application: Exit Sign, Security Equipment

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	$I_{\mathbf{F}}$	50	mA
Reverse Voltage	$v_{\mathbf{R}}$	4	V
Power Dissipation	$P_{\mathbf{D}}$	125	mW
Operating Temperature Range	$T_{ m opr}$	-40~100	°C
Storage Temperature Range	$\mathrm{T_{stg}}$	-40~120	$^{\circ}\mathrm{C}$

CATHODE INDEX 1. ANODE 2. CATHODE **JEDEC** EIAJ TOSHIBA

Unit in mm

Weight: 0.31 g

ELECTRICAL AND OPTICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Forward Voltage	$V_{\mathbf{F}}$	$I_{ m F}=20{ m mA}$	_	2.05	2.5	V
Reverse Current	$_{ m I_R}$	$V_R = 4 V$	_	_	50	μ A
Luminous Intensity	IV	$I_{ m F}=20{ m mA}$	272	650	_	mcd
Peak Emission Wavelength	$\lambda_{\mathbf{p}}$	$I_{ m F}=20{ m mA}$	_	636	_	nm
Spectral Line Half Width	Δλ	$I_{ m F}=20{ m mA}$	_	20	_	nm
Dominant Wavelength	$^{\lambda}\mathrm{d}$	$ m I_F=20mA$	_	626	_	nm

Gallium arsenide (GaAs) is a substance used in the products described in this document. GaAs dust and fumes are toxic. Do not break, cut or pulverize the product, or use chemicals to dissolve them. When disposing of the products, follow the appropriate regulations. Do not dispose of the products with other industrial waste or with domestic

garbage.

The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any intellectual property or other rights of TOSHIBA CORPORATION or others.

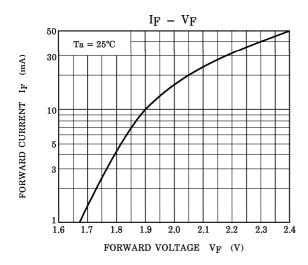
The information contained herein is subject to change without notice.

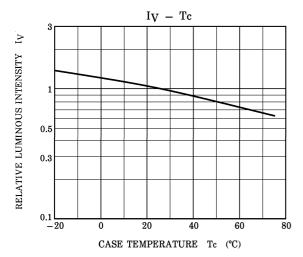
TOSHIBA is continually working to improve the quality and the reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to observe standards of safety, and to avoid situations in which a malfunction or failure of a TOSHIBA product could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent products specifications. Also, please keep in mind the precautions and conditions set forth in the TOSHIBA Semiconductor Reliability Handbook.

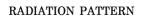
PRECAUTION

Please be careful of the followings

- Soldering temperature: 260°C max Soldering time: 3 s max (Soldering portion of lead: up to 2 mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5 mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light. If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.







 $Ta = 25^{\circ}C$

